

01-807

## IN THE CLAIMS

1. (currently amended) A method for forming a feature in a substrate, where residue within the feature can be easily removed, the method comprising the steps of:  
forming an upper sidewall portion of the feature by laser ablation, the upper  
sidewall portion forming a void in the substrate, where the upper sidewall  
portion has an upper sidewall angle, and  
forming a lower sidewall portion of the feature by laser ablation, the lower  
sidewall portion forming a void in the substrate, where the lower sidewall  
portion has a lower sidewall angle,  
where the upper sidewall angle of the upper sidewall portion is shallower than the  
lower sidewall angle of the lower sidewall portion.
2. (original) The method of claim 1, wherein the upper sidewall angle of the upper sidewall portion is from about thirty degrees to about sixty degrees.
3. (original) The method of claim 1, wherein the lower sidewall angle of the lower sidewall portion is from about sixty degrees to about ninety degrees.
4. (original) The method of claim 1, wherein the lower sidewall portion is formed before the upper sidewall portion is formed.
5. (cancelled) The method of claim 1, wherein the upper sidewall portion is formed by laser ablation of the substrate.
6. (cancelled) The method of claim 1, wherein the lower sidewall portion is formed by laser ablation of the substrate.
7. (original) The method of claim 1, wherein the feature comprises a blind bore formed in the substrate.
8. (original) The method of claim 1, wherein the upper sidewall portion has a depth of between about four microns and about eight microns.

01-807

9. (original) The method of claim 1, wherein the lower sidewall portion has a depth of between about four microns and about eight microns.
10. (original) The method of claim 1, wherein the feature has a depth of no more than about twelve microns.
11. (original) The method of claim 1, wherein the substrate comprises silicon.
12. (original) A feature formed according to the method of claim 1.
13. (original) An integrated circuit substrate having features formed according to the method of claim 1.
14. (currently amended) A method for forming indicia elements on a substrate, where the indicia elements have a shape that aids in removal of foreign material from the indicia elements on the substrate, the method comprising the steps of:
- forming an upper sidewall portion of the indicia elements by laser ablation, the upper sidewall portion forming a void in the substrate, where the upper sidewall portion has an upper sidewall angle,
- forming a lower sidewall portion of the indicia elements by laser ablation, the lower sidewall portion forming a void in the substrate, where the lower sidewall portion has a lower sidewall angle,
- where the upper sidewall angle of the upper sidewall portion is shallower than the lower sidewall angle of the lower sidewall portion, and
- forming the indicia elements in a pattern to form identifying indicia on the substrate.
15. (original) The method of claim 14, wherein all of the upper sidewall portions of all of the indicia elements are formed prior to forming any of the lower sidewall portions of any of the indicia elements.
16. (original) The method of claim 14, wherein all of the lower sidewall portions of all of the indicia elements are formed prior to forming any of the upper sidewall portions of any of the indicia elements.

01-807

17. (original) The method of claim 14, wherein a preceding one of the indicia elements is completely formed prior to forming a succeeding one of the indicia elements.

18. (currently amended) The method of claim 14, wherein:

~~the upper sidewall portion is formed by laser ablation of the substrate and the~~  
upper sidewall angle of the upper sidewall portion is from about thirty degrees to about sixty degrees.

~~the lower sidewall portion is formed by laser ablation of the substrate and the~~  
lower sidewall angle of the lower sidewall portion is from about sixty degrees to about ninety degrees,

the upper sidewall portion has a depth of between about four microns and about eight microns,

the lower sidewall portion has a depth of between about four microns and about eight microns, and

the indicia element is a blind bore formed in the substrate and has a depth of no more than about twelve microns.

19. (original) An integrated circuit substrate having identifying indicia formed according to the method of claim 14.

20. (cancelled) Identifying indicia on a substrate, the identifying indicia formed with a pattern of indicia elements, where the indicia elements have a shape that aids in removal of foreign material from the indicia elements on the substrate, each indicia element forming a blind bore in the substrate, and having a sidewall with a sidewall angle of between about thirty degrees and about sixty degrees, and having a depth of no more than about twelve microns.